

# DCR3900H65

# **Phase Control Thyristor**

Replaces DS6064-1 DS6064-2 June 2019 (LN38878)

### **FEATURES**

- Double Side Cooling
- High Surge Capability

### **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>DSM</sub> and V <sub>RSM</sub> V	Conditions
DCR3900H65 DCR3900H62 DCR3900H58 DCR3900H54	6500 6200 5800 5400	$\begin{split} T_{vj} = -40^{\circ}\text{C to } 110^{\circ}\text{C}, \\ I_{DRM} = I_{RRM} = 700\text{mA}, \\ V_{DRM}, V_{RRM}  t_p = 10\text{ms}, \\ V_{DRM}  \&  V_{RRM} = \\ V_{DSM}  \&  V_{RSM} - 900V \\ respectively \end{split}$

Lower voltage grades available.

### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

### DCR3900H65

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

### **KEY PARAMETERS**

$V_{DRM}$	6500 V
$I_{T(AV)}$	3900 A
I <sub>TSM</sub>	71000 A
dV/dt*	2000 V/µs
dI/dt	200 A/μs

### \* Higher dV/dt selections available

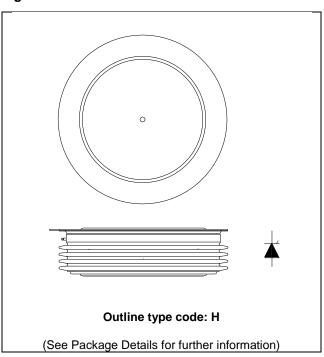


Fig. 1 Package outline

www.dynexsemi.com 1/9

# **CURRENT RATINGS**

## $T_{\text{case}}$ = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions		Units	
Double Si	Double Side Cooled				
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	3900	А	
I <sub>T(RMS)</sub>	RMS value	-	6120	Α	
lτ	Continuous (direct) on-state current	-	5510	Α	

## **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 110^{\circ}C$	71.0	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	25.21	MA <sup>2</sup> s

# THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.004	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Double side cooled	DC	-	0.0008	°C/W
T <sub>vj</sub>	Virtual junction temperature	Blocking V <sub>DRM</sub> / <sub>VRRM</sub>		-40	110	°C
T <sub>stg</sub>	Storage temperature range			-40	140	°C
F <sub>m</sub>	Clamping force			110	130	kN

www.dynexsemi.com 2/9

# **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 110°C		-	700	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V <sub>DRM</sub> , T <sub>j</sub> = 110°C, gate open		2000	-	V/µs
dI/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 4000A	Repetitive 50Hz	-	200	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	1000	A/µs
		$t_r < 0.5 \mu s, T_j = 110 ^{\circ} C$				
V <sub>T</sub>	On-state voltage	I <sub>T</sub> = 3000A, T <sub>case</sub> = 110°C			1.69	٧
V <sub>T(TO)</sub>	Threshold voltage	T <sub>case</sub> = 110°C		-	1.13	٧
r <sub>T</sub>	On-state slope resistance	T <sub>case</sub> = 110°C		-	0.185	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% \ V_{DRM}$ , gate source 30V, $10\Omega$		-	3.0	μs
	,	$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j = 110$ °C, $V_R = 100$ V, $dI/dt = 1.5$ A/µs,		-	1000	μs
		dV <sub>DR</sub> /dt = 20V/μs linear to 67% V <sub>DRM</sub>				
Qs	Stored charge	$I_T = 2000A$ , $tp = 1000us$ , $T_j = 110$ °C, $dI/dt = 1.5A/\mu s$ ,		-	5750	μC
I <sub>RR</sub>	Reverse recovery current			-	95	Α
lι	Latching current	$T_j = 25$ °C,		-	1	Α
l <sub>Η</sub>	Holding current	$T_j = 25$ °C,		-	200	mA

# **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol	Parameter Test Conditions		Max.	Units
$V_{GT}$	Gate trigger voltage	V <sub>DRM</sub> = 5V, T <sub>case</sub> = 25°C	2.6	V
$V_{GD}$	Gate non-trigger voltage	At 40% V <sub>DRM</sub> , T <sub>case</sub> = 110°C	0.3	V
I <sub>GT</sub>	Gate trigger current	V <sub>DRM</sub> = 5V, T <sub>case</sub> = 25°C	400	mA
I <sub>GD</sub>	Gate non-trigger current	At 40% V <sub>DRM</sub> , T <sub>case</sub> = 110°C	20	mA

www.dynexsemi.com 3/9

### **CURVES**

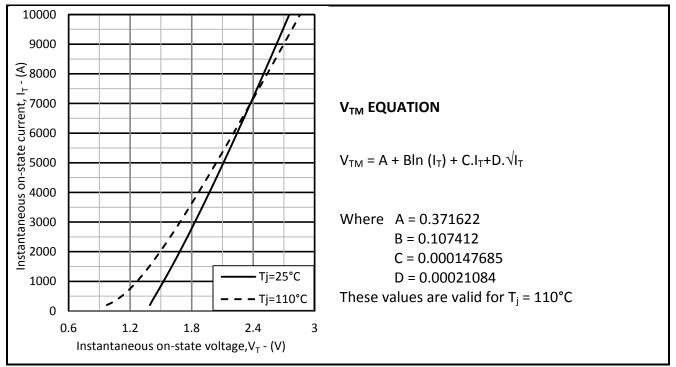


Fig.2 Maximum &minimum on-state characteristics

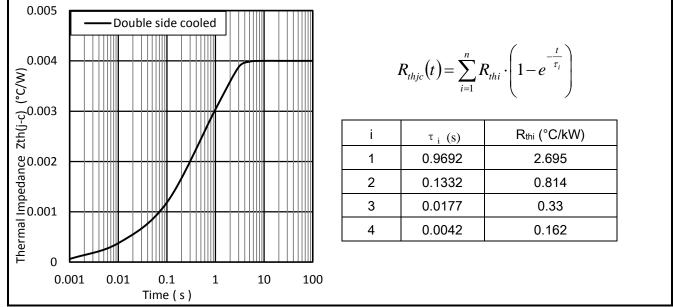
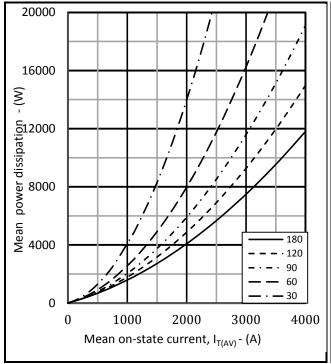


Fig.3 Maximum (limit) transient thermal impedance - junction to case (°C/W)

www.dynexsemi.com 4/9



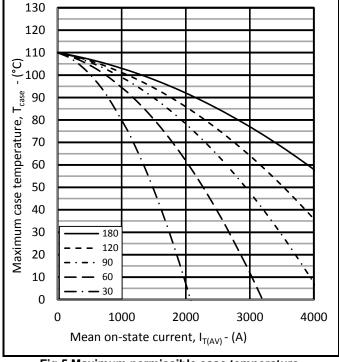


Fig.4 On-state power dissipation – sine wave

Fig.5 Maximum permissible case temperature, double side cooled – sine wave

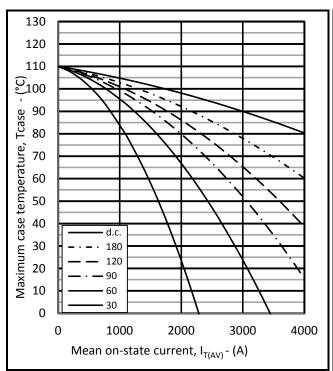


Fig.6 Maximum permissible case temperature, double side cooled – rectangular wave

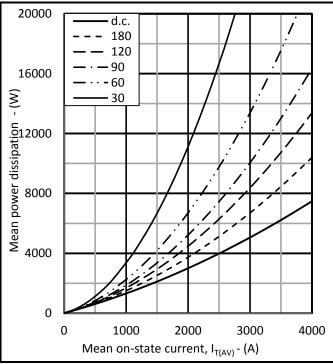
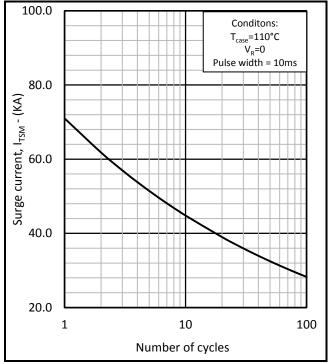


Fig.7 On-state power dissipation - rectangular wave

www.dynexsemi.com 5/9



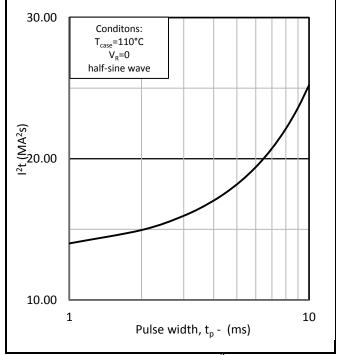


Fig.8 Multi-cycle surge current

Fig.9 Single-cycle I<sup>2</sup>t

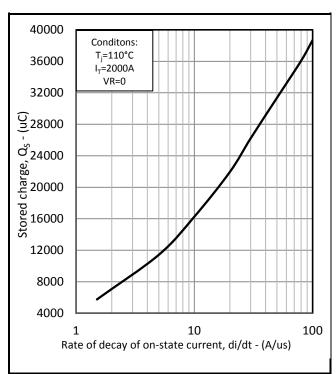


Fig.10 Stored charge vs di/dt

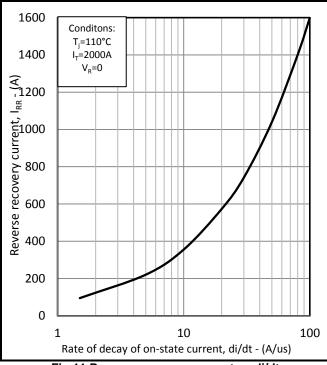


Fig.11 Reverse recovery current vs di/dt

www.dynexsemi.com 6/9

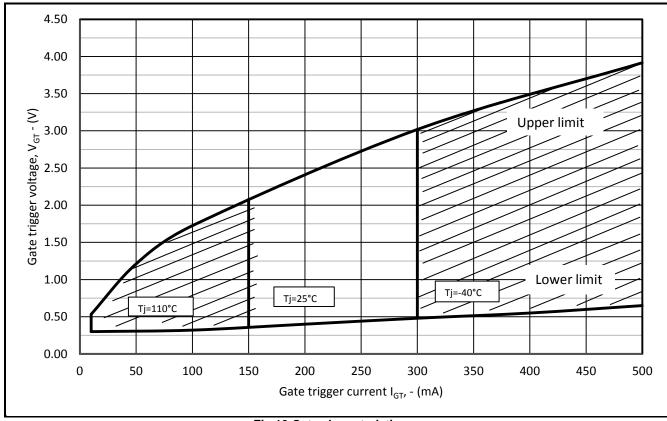


Fig.10 Gate characteristics

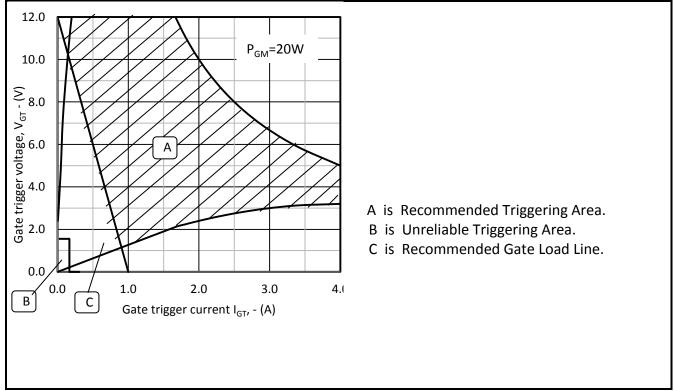


Fig.11 Gate characteristics

www.dynexsemi.com 7/9

## **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

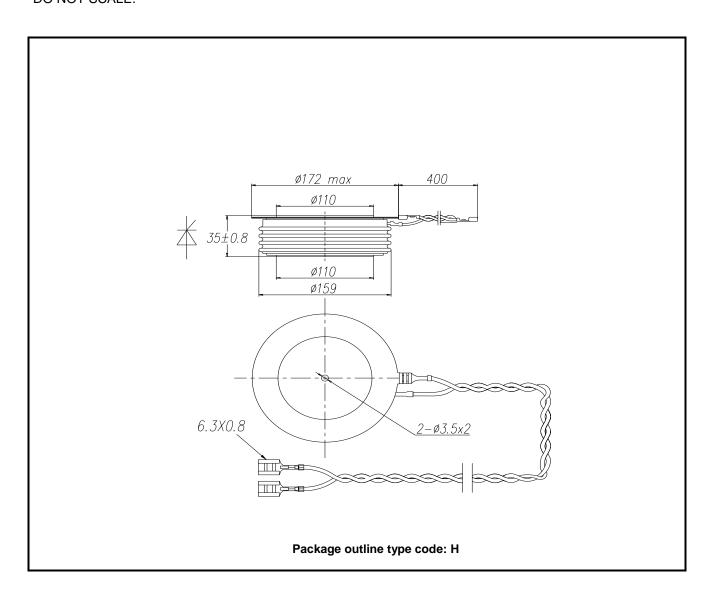


Fig.12 Package outline

www.dynexsemi.com 8/9

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www.dynexsemi.com 9/9